Synopsis pattern – General requirements

Please read these instructions carefully!

Deadline for submission is 15 October 2025.

General instructions:

The number of pages should not exceed 3 pages and 5 MB.

Important: the length of the title is limited to a maximum of 100 characters including spaces.

Please capitalize the initial letters of your title except prepositions and articles.

Each page should be a single column on European A4 size (210 mm $\times$ 297 mm).

The margins have to be set up as follows:

Top margin to the first line:	2.2 cm
Bottom margin to the last line:	3.0 cm
Left margin to the text:	1.7 cm
Right margin to the text:	1.7 cm

Please ensure that all fonts and pictures or tables are embedded in the final PDF-file.

We recommend to use the following pattern to produce your synopsis for PCIM Conference Seminars.

After your synopsis is written, please submit your synopsis as PDF-file online.

How to LaTeX:

This document compiles successfully with pdfLaTeX and TeX Live 2024 (generated with Overleaf).

Your Seminar Title – (max. 100 characters incl. spaces) Please Capitalize the Initial Letters of Your Title Except Prepositions and Articles

Seminar instructor: Instructor's first name and surname, e-mail address
2nd instructor's first name and surname, e-mail address 2
3rd instructor's first name and surname, e-mail address 3

1 Synopsis

Here, you start to write the synopsis (short form) of the real paper. It consists of an introduction, the body of the text with the different paragraphs, including figures, formula, tables, images and the conclusion.

The synopsis is an extended summary of your seminar. You may describe which topic will be presented and which possible solutions, problems or outcomes can be expected by attending the seminar. It should give a clear idea of what to expect in the seminar.

The guidelines and requirements for a synopsis submitted to PCIM Conference are:

- The instructor(s) obtain company and governmental clearance prior to submission of the synopsis.
- Synopses marked or labeled as "Confidential", "Proprietary" or with similar wording will not be accepted.
- Synopses can be submitted in any version of Adobe Acrobat.pdf
- Number all pages of the synopsis.

2 Quick tips

Figures are usually referenced by the abbreviated from with a space between Fig. and the number, i.e., “see Fig. 1”. Only when a sentence begins with the reference, figure is spelled out: “Figure 2 shows the relation between. . . ”.

The same applies to equations, i.e. “As shown in Eq. (1). . . ” and “Equation (1) describes the relation. . . ”.

$$R_{\mathrm{th}} = \frac{\Delta T}{P_V} = 10\,\mathrm{K/W} \tag{1}$$

The last section in your paper collects the references to literature, listed in the order of appearance in the text. They are marked in the text with the number in square brackets [1].

In the reference list, each publication is given with the list of authors, followed by the title, the name of the conference proceedings or journal, the year of publication and the page numbers. If more than 5 authors are involved [2], the list is reduced to the first 5 authors followed by “et al.”.

Links to web sites should be avoided in the reference list since they are subject to change. References to digital documents should use the ‘Digital Objects Identifier’ (DOI) [3].

References to papers in scientific journals should state the volume of the journal and the year of publication [4].

3 This is a 1st Order Heading

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Fig. 1: This is the caption of an image. It describes the content of the illustration or graph.

(a) (b)

Fig. 2: This is the caption of an image. It describes the content of the illustration or graph.

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References

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[2] H. Kabza, H. .-. Schulze, Y. Gerstenmaier, P. Voss, J. W. W. Schmid, *et al.*, “Cosmic radiation as a cause for power device failure and possible countermeasures,” in *Proceedings of the 6th International Symposium on Power Semiconductor Devices and Ics*, May 1994, pp. 9–12. DOI: 10.1109/ISPSD.1994.583620.

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[4] S. Ramminger, N. Seliger, and G. Wachutka, “Reliability model for al wire bonds subjected to heel crack failures,” *Microelectronics Reliability*, vol. 40, no. 8, pp. 1521–1525, 2000, Reliability of Electron Devices, Failure Physics and Analysis. DOI: https://doi.org/10.1016/S0026-2714(00)00139-6.